SENSITRON SEMICONDUCTOR

Powered by Sensitron











CUSTOM HYBRIDS

For use in all Hi-Rel Applications-Space, Military, Medical, Aerospace

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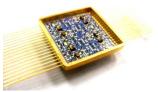
Hermetic Custom Hybrids _____

Sensitron's Hermetic Custom Hybrid Devices offer the highest performance to space ratio, and are superior to competing technologies. Dependent on your space and size constraints, Sensitron offers Custom Hybrids specific to your design requirements. Sensitron is positioned as a world leader in the advanced technology industry, with products that are designed, manufactured, tested, and qualified for applications where size, weight, and reliability are critical to mission success. Sensitron is a qualified MIL-STD-38534 Class H & Class K Facility.

Product Features:

- ✓ Superior thermal performance and high power density
- ✓ Flexible design configurations and various power device options
- Best performance/space ratio over competing technologies
- Sophisticated advanced simulation and modeling tools with an R&D team

Chip & Wire



Small Signal Hybrid

- ✓ Flexible packaging options
- ✓ High electrical conductivity
- ✓ Power semiconductor construction capable
- √ Flexible bare chips and chip parts selection
- ✓ Automation friendly

Hermetic Power Hybrid Packaging



- Half-Bridge IGBT Module
- ✓ Electrically islolated package
- √ Mechanical strength
- ✓ Metal shielding
- √ Thermal resistivity

Baseless Packaging



- Lower profile and light weight
- √ Lowest possible thermal resistance
- ✓ Higher temperature applications
- ✓ Lower cost
- ✓ Automation friendly

Ultrafast 3-Phase Bridge



Hermetic Custom Hybrids _____

Integrated Heat Sink Packaging



Half-Bridge Motor Module

- √ High transient power capability
- √ Very compact package
- √ Thermal resistivity
- ✓ Multiplayer structure capable
- ✓ Integrated, cross-hatched heat sink for greater efficiency

Small Area Devices

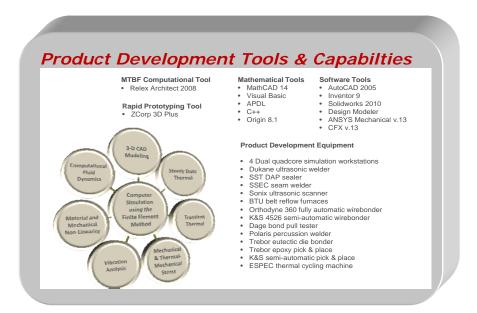


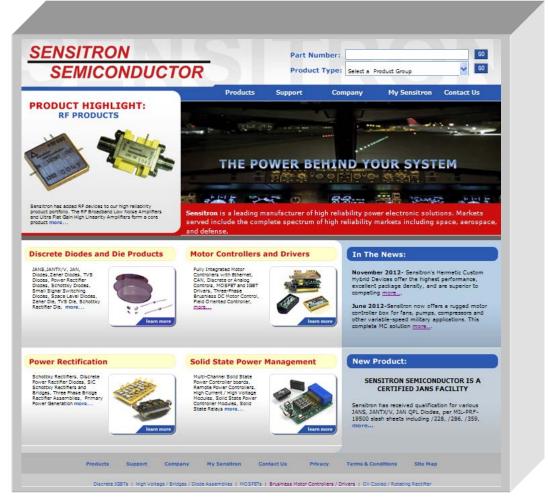
Space Level Diode Array

- ✓ Electrically isolated package
- √ Flexible bare chip and die selection
- √ Mechanical strength
- ✓ Power semicondutor construction capable
- ✓ Automation friendly

Attribute Comparison by Hybrid Design

	Description	Baseless	Chip & Wire	Int Heat Sink	Power Hybrid	Small Area Devices
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1	Electrically islolated package	√		√	√	√
2	Flexible packaging options	√	√	√	√	
3	Multilayer structure capable	√		√	√	
4	Flexible bare chips selection	√	√		√	√
5	Flexible chip parts selection	√	√		√	
6	Automation friendly	√	√			√
7	Metal shielding		√		√	
8	High electrical conductivity	√	√	√	√	
9	Power semiconductor construction capable	√	√		√	√
10	Fine line pattern	√	√	√	√	√
11	Lead wire bond ability and strength		√			
12	Thermal resistivity	√		√	√	
13	Resistance range of resistor	√		√	√	
14	Resistor trimming	√	√	√	√	√
15	Freedom of resistor trimming		√	√		
16	Flatness	√	√	√		√
17	Dimensional accuracy	√	√	\checkmark	√	√
18	Mechanical strength		√		√	√





Visit online at: www.sensitron.com

About Sensitron: Sensitron is a leading manufacturer of high reliability power electronic solutions including motor controllers, diodes, smart power management and conversion, voltage protection components and embedded boards, with over 40 years heritage serving space, aerospace, and defense markets.